**Preferred Device** 

### **Triacs**

### **Silicon Bidirectional Thyristors**

Designed primarily for full-wave ac control applications, such as motor controls, heating controls or dimmers; or wherever full-wave, silicon gate-controlled devices are needed.

- Uniform Gate Trigger Currents in Three Quadrants, Q1, Q2, and Q3
- High Commutating di/dt and High Immunity to dv/dt @ 125°C
- Minimizes Snubber Networks for Protection
- Blocking Voltage to 800 Volts
- On-State Current Rating of 12 Amperes RMS at 80°C
- High Surge Current Capability 100 Amperes
- Industry Standard TO-220AB Package for Ease of Design
- Glass Passivated Junctions for Reliability and Uniformity
- Device Marking: Logo, Device Type, e.g., MAC12HCD, Date Code

### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage <sup>(1)</sup> (T <sub>J</sub> = -40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	V <sub>DRM,</sub> V <sub>RRM</sub>	400	Volts
MAC12HCD MAC12HCM MAC12HCN		400 600 800	
On-State RMS Current (All Conduction Angles; T <sub>C</sub> = 80°C)	I <sub>T(RMS)</sub>	12	А
Peak Non-Repetitive Surge Current (One Full Cycle, 60 Hz, T <sub>J</sub> = 125°C)	I <sub>TSM</sub>	100	Α
Circuit Fusing Consideration (t = 8.33 ms)	l <sup>2</sup> t	41	A <sup>2</sup> sec
Peak Gate Power (Pulse Width ≤ 1.0 μs, T <sub>C</sub> = 80°C)	$P_{GM}$	16	Watts
Average Gate Power (t = 8.3 ms, T <sub>C</sub> = 80°C)	$P_{G(AV)}$	0.35	Watts
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

<sup>(1)</sup> V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

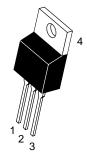


### ON Semiconductor™

http://onsemi.com

# TRIACS 12 AMPERES RMS 400 thru 800 VOLTS





TO-220AB CASE 221A STYLE 4

PIN ASSIGNMENT				
1	Main Terminal 1			
2	Main Terminal 2			
3	Gate			
4	Main Terminal 2			

### **ORDERING INFORMATION**

Device	Package	Shipping
MAC12HCD	TO220AB	50 Units/Rail
MAC12HCM	TO220AB	50 Units/Rail
MAC12HCN	TO220AB	50 Units/Rail

**Preferred** devices are recommended choices for future use and best overall value.

### THERMAL CHARACTERISTICS

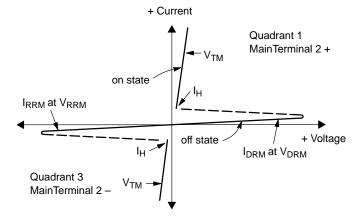
Characteristic	Symbol	Value	Unit
Thermal Resistance			°C/W
— Junction to Case	$R_{\theta JC}$	2.2	
— Junction to Ambient	$R_{\theta JA}$	62.5	
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Peak Repetitive Blocking Current $(V_D = Rated\ V_{DRM},\ V_{RRM},\ Gate\ Open) \\ T_J = 25^{\circ}C \\ T_J = 125^{\circ}C$	I <sub>DRM</sub> , I <sub>RRM</sub>	_	_ _	0.01 2.0	mA
ON CHARACTERISTICS					
Peak On-State Voltage <sup>(1)</sup> $(I_{TM} = \pm 17 \text{ A})$	V <sub>TM</sub>	_	_	1.85	V
Gate Trigger Current (Continuous dc) ( $V_D$ = 12 V, $R_L$ = 100 $\Omega$ ) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)	I <sub>GT</sub>	10 10 10	_ _ _	50 50 50	mA
Holding Current ( $V_D = 12 \text{ V}$ , Gate Open, Initiating Current = $\pm 150 \text{ mA}$ )	I <sub>H</sub>	_	_	60	mA
Latch Current ( $V_D$ = 12 V, $I_G$ = 50 mA) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)	ΙL	_ _ _	_ _ _	60 80 60	mA
Gate Trigger Voltage (Continuous dc) ( $V_D$ = 12 V, $R_L$ = 100 $\Omega$ ) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)	V <sub>GT</sub>	0.5 0.5 0.5	_ _ _	1.5 1.5 1.5	V
DYNAMIC CHARACTERISTICS					
Rate of Change of Commutating Current ( $V_D$ = 400 V, $I_{TM}$ = 4.4 A, Commutating dv/dt = 18 V/ $\mu$ s, Gate Open, $T_J$ = 125°C, $f$ = 250 Hz, $C_L$ = 10 $\mu$ F, $L_L$ = 40 mH, with Snubber)	(di/dt) <sub>c</sub>	15	_	_	A/ms
Critical Rate of Rise of Off-State Voltage $(V_D = Rated\ V_{DRM},\ Exponential\ Waveform,\ Gate\ Open,\ T_J = 125^\circ C)$		600	_	_	V/µs
Repetitive Critical Rate of Rise of On-State Current IPK = 50 A; PW = 40 µsec; diG/dt = 200 mA/µsec; f = 60 Hz	di/dt	_	_	10	A/μs

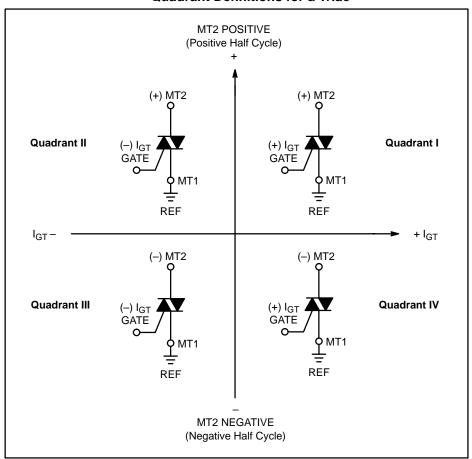
<sup>(1)</sup> Pulse Test: Pulse Width ≤ 2.0 ms, Duty Cycle ≤ 2%.

## Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
$V_{RRM}$	Peak Repetitive Reverse Off State Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Maximum On State Voltage
I <sub>H</sub>	Holding Current



### **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.

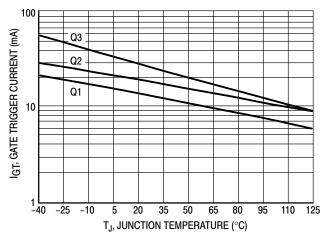


Figure 1. Typical Gate Trigger Current versus Junction Temperature

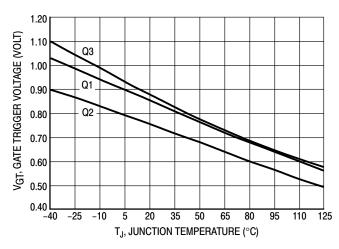


Figure 2. Typical Gate Trigger Voltage versus Junction Temperature

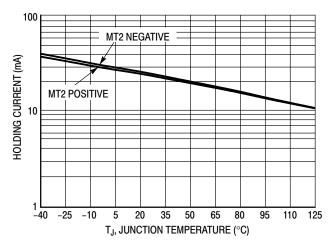


Figure 3. Typical Holding Current versus Junction Temperature

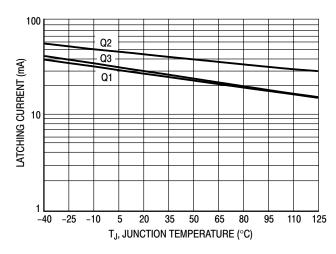


Figure 4. Typical Latching Current versus Junction Temperature

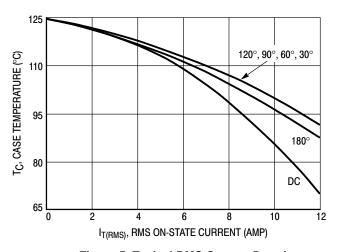


Figure 5. Typical RMS Current Derating

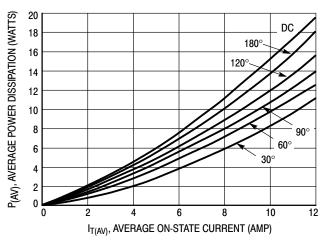


Figure 6. On-State Power Dissipation

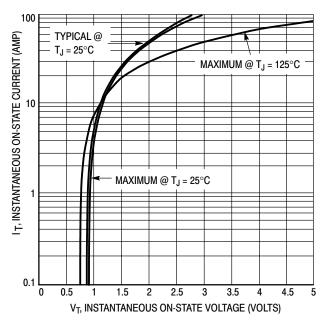


Figure 7. Typical On-State Characteristics

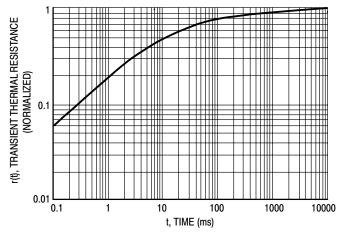
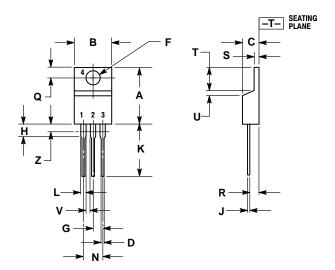


Figure 8. Typical Thermal Response

### **PACKAGE DIMENSIONS**

TO-220 CASE 221A-09 **ISSUE AA** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLING DIMENSION: INCH.
  3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 4:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. MAIN TERMINAL 2



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